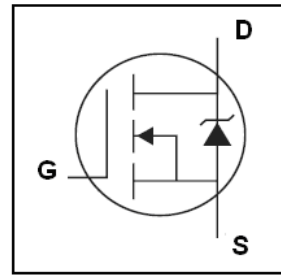


Features

- ◆ Low On-Resistance
- ◆ Fast Switching
- ◆ 100% Avalanche Tested
- ◆ Repetitive Avalanche Allowed up to Tjmax
- ◆ Lead-Free, RoHS Compliant

Description

VS40280AT designed by the trench processing techniques to achieve extremely low on-resistance. Additional features of this design are a 175°C junction operating temperature, fast switching speed and improved repetitive avalanche rating . These features combine to make this design an extremely efficient and reliable device for use in Automotive applications and a wide variety of other applications.



V_{DSS}	40V
$R_{DS(on)}$	1.8 mΩ
I_D	280A


Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (TA) is 25°C, unless otherwise specified.

	Parameter	Rating	Unit
Common Ratings (Tc=25°C Unless Otherwise Noted)			
V_{GS}	Gate-Source Voltage	±20	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	40	V
T_J	Maximum Junction Temperature	175	°C
T_{STG}	Storage Temperature Range	-55 to 175	°C
I_S	Diode Continuous Forward Current ^① ③	$T_C = 25^\circ C$ 280	A
Mounted on Large Heat Sink			
I_{DM}	Pulse Drain Current Tested (Silicon Limit)	$T_C = 25^\circ C$ 1120	A
I_D	Continuous Drain current@ $V_{GS}=10V$ (See Fig2) ③	$T_C = 25^\circ C$ 280	A
		$T_C = 100^\circ C$ 200	
P_D	Maximum Power Dissipation	$T_C = 25^\circ C$ 350	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	0.78	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	62.5	°C/W
Drain-Source Avalanche Ratings			
EAS	Avalanche Energy, Single Pulsed ②	1100	mJ

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	40	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current(Tc=25°C)	V _{DS} =40V,V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(Tc=125°C)	V _{DS} =40V,V _{GS} =0V	--	--	100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V,V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =250μA	1	2	3	V
R _{DS(ON)}	Drain-Source On-State Resistance①	V _{GS} =10V, I _D =90A	--	1.8	2.5	mΩ
gfs	Forward Transconductance	V _{DS} = 25V, I _D =90A	--	80	--	S
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =20V,V _{GS} =0V, f=1MHz	--	6650	--	pF
C _{oss}	Output Capacitance		--	1100	--	pF
C _{rss}	Reverse Transfer Capacitance		--	445	--	pF
Q _g	Total Gate Charge	V _{DS} =20V,I _D =30A, V _{GS} =10V	--	155	--	nC
Q _{gs}	Gate-Source Charge		--	35	--	nC
Q _{gd}	Gate-Drain Charge		--	56	--	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =20V, I _D =1A, R _G =6.8Ω, V _{GS} =10V R _L =30Ω,	--	39	--	nS
t _r	Turn-on Rise Time		--	35	--	nS
t _{d(off)}	Turn-Off Delay Time		--	110	--	nS
t _f	Turn-Off Fall Time		--	63	--	nS
Source- Drain Diode Characteristics @ T_J = 25°C (unless otherwise stated)						
I _{SD}	Source-drain current(Body Diode) ①	T _c =25°C	--	--	280	A
V _{SD}	Forward on voltage	I _{SD} =60A,V _{GS} =0V	--	--	1.3	V
t _{rr}	Reverse Recovery Time	T _J =25°C,I _{sd} =30A, V _{GS} =0V di/dt=100A/μs	--	85	--	nS
Q _{rr}	Reverse Recovery Charge		--	125	--	nC

NOTE:

①Pulse width ≤ 300μs; duty cycles ≤ 2%.

② Limited by T_{Jmax}, starting T_J = 25°C, L = 0.25mH,R_G = 25Ω, I_{AS} = 98A, V_{GS} =10V.

Part not recommended for use above this value

③Repetitive rating; pulse width limited by max. junction temperature.Package limit continuous current is 75A.

Typical Characteristics

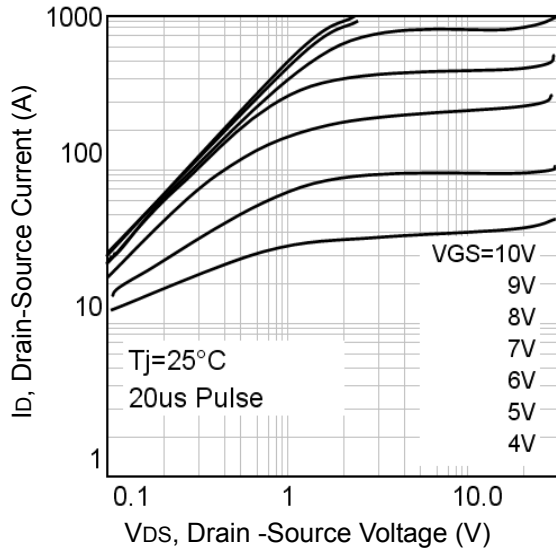


Fig1. Typical Output Characteristics

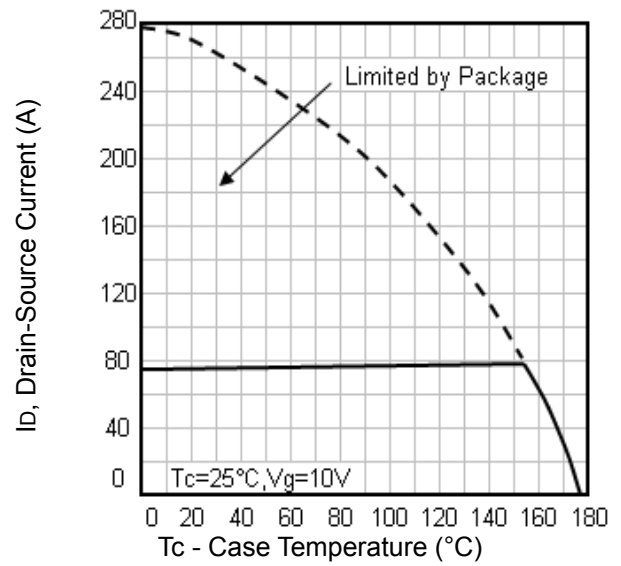


Fig2. Maximum Drain Current Vs. Case Temperature

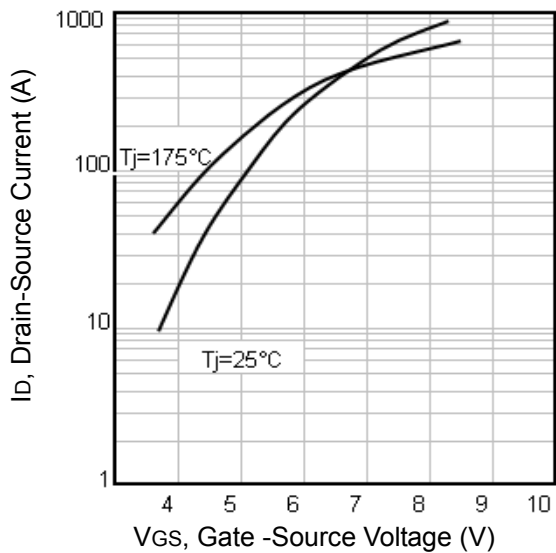


Fig3. Typical Transfer Characteristics

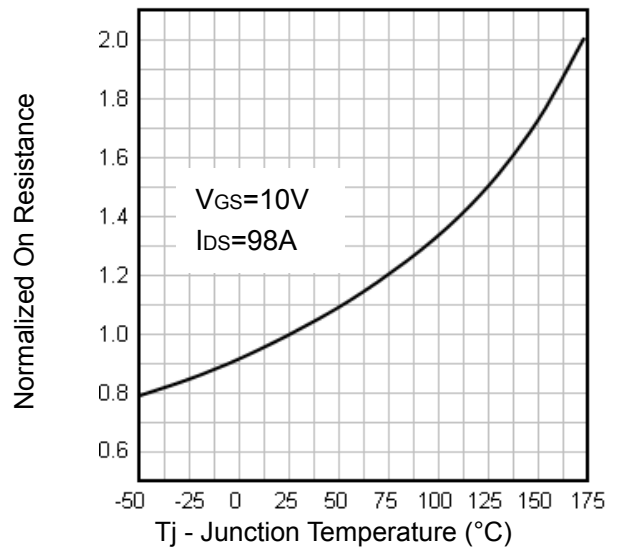


Fig4. Normalized On-Resistance Vs. Temperature

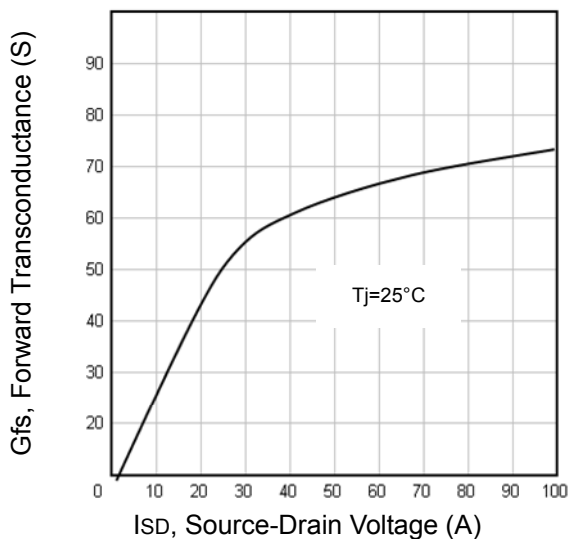


Fig5. Typical Forward Transconductance Vs. Drain Current

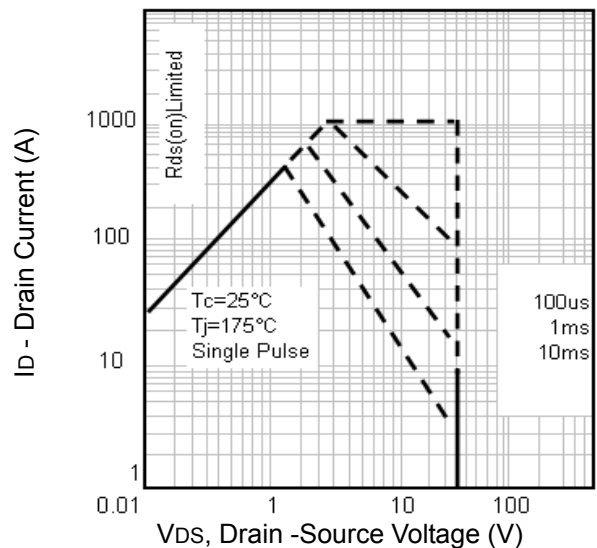


Fig6. Maximum Safe Operating Area

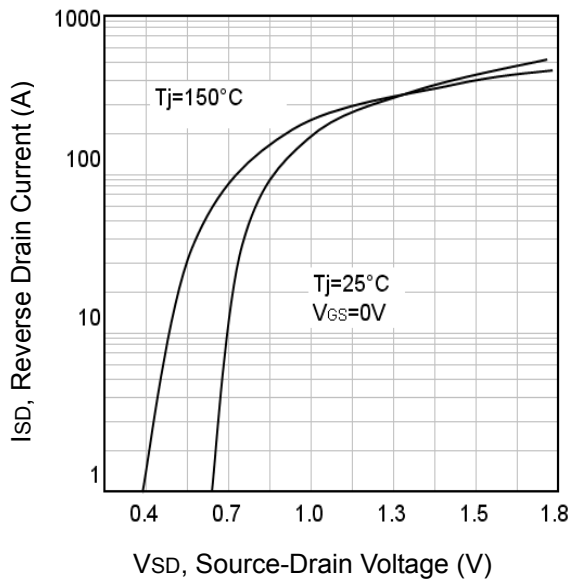


Fig7. Typical Source-Drain Diode Forward Voltage

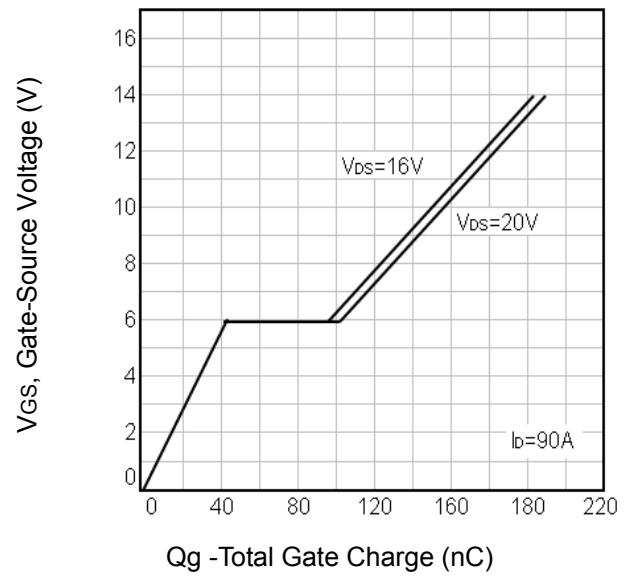


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

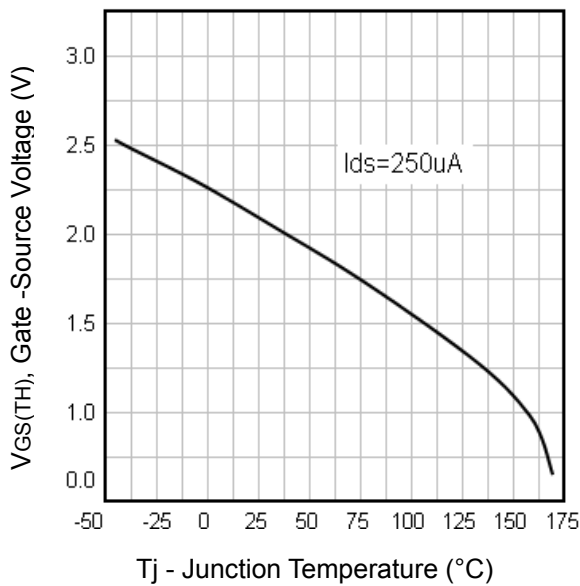


Fig9. Threshold Voltage Vs. Temperature

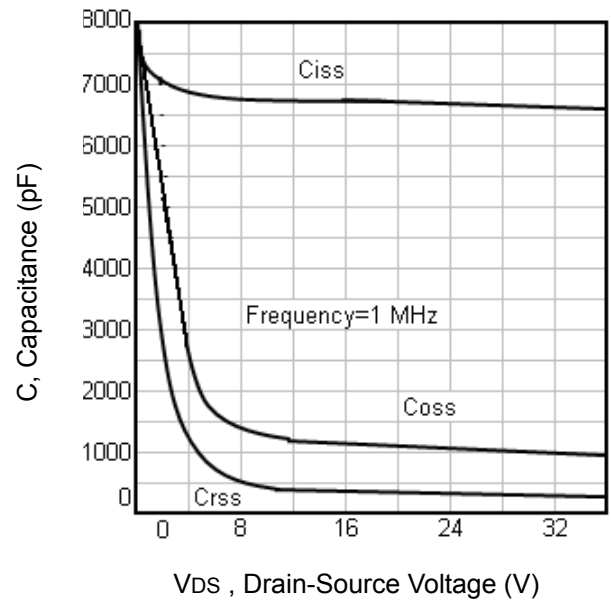


Fig10. Typical Capacitance Vs. Drain-Source Voltage

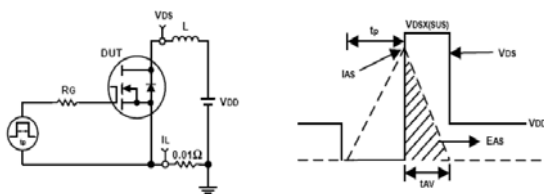


Fig11. Unclamped Inductive Test Circuit and waveforms

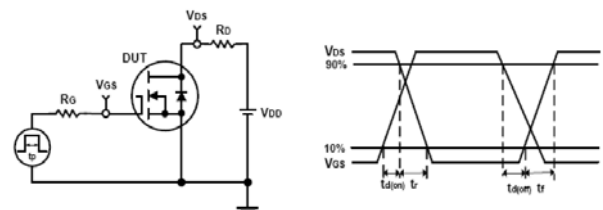
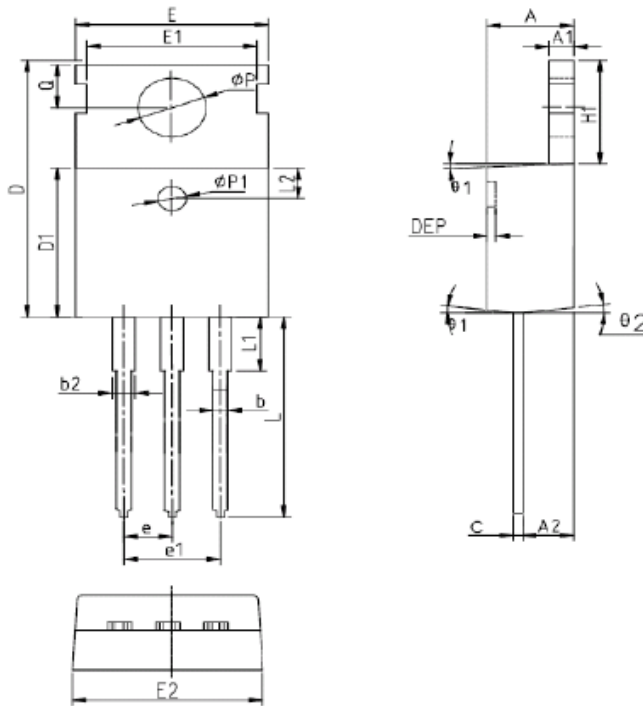


Fig12. Switching Time Test Circuit and waveforms

TO-220 Package Outline



SYMBOL	MM		
	MIN	NOM	MAX
A	4.40	4.57	4.70
A1	1.27	1.30	1.33
A2	2.35	2.40	2.50
b	0.77	-	0.90
b2	1.23	-	1.36
C	0.48	0.50	0.52
D	15.40	15.60	15.80
D1	9.00	9.10	9.20
DEP	0.05	0.10	0.20
E	9.70	9.90	10.10
E1	-	8.70	-
E2	9.80	10.00	10.20
$\phi p1$	1.40	1.50	1.60
e	2.54BSC		
e1	5.08BSC		
H1	6.40	6.50	6.60
L	12.75	-	13.17
L1	-	-	3.95
L2	2.50REF.		
ϕp	3.57	3.60	3.63
Q	2.73	2.80	2.87
$\theta 1$	5°	7°	9°
$\theta 2$	1°	3°	5°

Order Information

Product	Marking	Package	Packaging	Min Unit Quantity
VS40280AT	VS40280AT	TO-220	50PCS/Tube	1000PCS

Customer Service

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